

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Reza A. Pagaila</td> <td>07/13/2010</td> </tr> <tr> <td>Daesik Choi</td> <td>07/13/2010</td> </tr> <tr> <td>Jun Mo Koo</td> <td>07/13/2010</td> </tr> </tbody> </table>		Name	Execution Date	Reza A. Pagaila	07/13/2010	Daesik Choi	07/13/2010	Jun Mo Koo	07/13/2010				
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>STATS ChipPAC, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>10 Ang Mo Kio Street 65</td> </tr> <tr> <td>Internal Address:</td> <td>#05-17/20 Techpoint</td> </tr> <tr> <td>City:</td> <td>Singapore</td> </tr> <tr> <td>State/Country:</td> <td>SINGAPORE</td> </tr> <tr> <td>Postal Code:</td> <td>569059</td> </tr> </table>		Name:	STATS ChipPAC, Ltd.	Street Address:	10 Ang Mo Kio Street 65	Internal Address:	#05-17/20 Techpoint	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	569059
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (602)748-4414  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 602-748-4408        Email: main@plgaz.com        Correspondent Name: Robert D. Atkins        Address Line 1: 605 W. Knox Road        Address Line 2: Suite 104        Address Line 4: Tempe, ARIZONA 85284</p>													
ATTORNEY DOCKET NUMBER:	2515.0233												
NAME OF SUBMITTER:	Robert D. Atkins												
Total Attachments: 3													

OP \$40.00 12837562

**501234524**

**PATENT**  
**REEL: 024695 FRAME: 0195**

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ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, DAESIK CHOI of Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PROTECTIVE LAYER OVER EXPOSED SURFACES OF SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0233, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for DAESIK CHOI

Witnessed on this date:

July 13'10

Signature of Witness:



Printed Name of Witness:

Lee Hyung Min

Address of Witness:

2807-102, Mubryun Village, Sang-dong,  
Gumi-gu, Bucheon-Gyeonggi-do, Korea

# ASSIGNMENT AND AGREEMENT

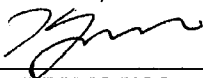
For good and valuable consideration, the receipt of which is hereby acknowledged, I, JUN MO KOO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PROTECTIVE LAYER OVER EXPOSED SURFACES OF SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0233, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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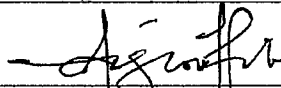


Signature for JUN MO KOO

Witnessed on this date:

13 JUL. 2010

Signature of Witness:



Printed Name of Witness:

DIOSCORO MERILO

Address of Witness:

5 YISHUN ST. 23

SINGAPORE 768442

# ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, REZA A. PAGAILA of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING PROTECTIVE LAYER OVER EXPOSED SURFACES OF SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0233, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

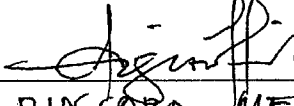
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Signature for REZA A. PAGAILA

Witnessed on this date: 13 JUL. 2010  
Signature of Witness:   
Printed Name of Witness: DIOSCORO MERILO  
Address of Witness: 5 YUSHUN ST. 23  
SINGAPORE 768442